

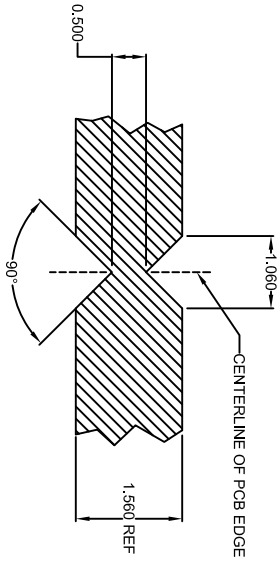
CROSS-SECTION  
SUBSTRATE

<b>CUSTOMER NOTICE</b>				CONTRACT NO.	
LINEAR TECHNOLOGY HAS MADE A BEST EFFORT TO DESIGN A CIRCUIT THAT MEETS CUSTOMER-SUPPLIED SPECIFICATIONS; HOWEVER, IT REMAINS THE CUSTOMER'S RESPONSIBILITY TO VERIFY PROPER AND RELIABLE OPERATION IN THE ACTUAL APPLICATION. COMPONENT SUBSTITUTION AND PRINTED CIRCUIT BOARD LAYOUT MAY SIGNIFICANTLY AFFECT CIRCUIT PERFORMANCE OR RELIABILITY. CONTACT LINEAR TECHNOLOGY APPLICATIONS ENGINEERING FOR ASSISTANCE.				APPROVALS	
				PCB DES. GRIFFITHS	
				ENG. D. STUETZLE	
THIS CIRCUIT IS PROPRIETARY TO LINEAR TECHNOLOGY AND SUPPLIED FOR USE WITH LINEAR TECHNOLOGY PARTS.				DATE:	
14-Bit, 125 Msps Quad ADC with Integrated Drivers				TITLE: SCHEMATIC	
SIZE				IC NO.	REV
B				DEMOCIRCUIT DC1732B	0
Monday, December 12, 2011				SHEET	12 OF 15

**TITLE: SCHEMATIC**  
**14-Bit, 125 Msps Quad ADC with Integrated Drivers**

NOTES: UNLESS OTHERWISE SPECIFIED.

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. VIA WALL COPPER THICKNESS TO BE 0.030 MIN.
- 3. PLATING: IMMERSION GOLD BOTH SIDES.
  - NI - 0.003 MINIMUM TO 0.005 MAXIMUM.
  - AU - 0.0001 MINIMUM TO 0.0003 MAXIMUM.
- 4. PCB TO BE ELECTRICALLY TESTED. USE CAPTURED GERBER DATA PROVIDED.
- 5. DELETED.
- 6. CORE MATERIAL - FR4, 4 LAYER, 1oz Cu INTERNAL LAYERS, 1oz Cu + PLATING EXTERNAL LAYERS
- 7. SOLDERMASK - LPI, GREEN, BOTH SIDES. POSITIONAL TOLERANCE = +/-0.050MM
- 8. GERBER DATA SUPPLIED IN RS-274X FORMAT.
- 9. INTERPRET GERBER LAYERS AS FOLLOWS:
  - M1 - TOP COMPONENT SIDE METALIZATION - 100 OHM DIFFERENTIAL IMPEDANCE
  - M2 - INNER LAYER METAL
  - M3 - INNER LAYER METAL - 100 OHM DIFFERENTIAL IMPEDANCE
  - M4 - BOTTOM LAYER METAL - 100 OHM DIFFERENTIAL IMPEDANCE
  - S1 - SOLDERMASK LAYER 1
  - S4 - SOLDERMASK LAYER 4
  - DRILL - THRU HOLE MECHANICAL DRILL
  - P1 - SOLDER PASTE TOP COMPONENT SIDE (LAYER 1)
  - P4 - SOLDER PASTE BOTTOM COMPONENT SIDE (LAYER 4)
  - PCB - PCB OUTLINE
  - L1 - LEGEND LAYER 1 (TOP COMPONENT SIDE)
  - L4 - LEGEND LAYER 4 (BOTTOM COMPONENT SIDE)
- 10. MODIFICATION OF ARTWORK REQUIRES LINEAR TECHNOLOGY AUTHORIZATION.
- 11. VENDOR TO SUPPLY PANELIZED PCB'S IN A 3X2 OR 3X3 MATRIX. SEE DETAIL "A".
- 12. CROSS-SECTION OF PCB MUST BE NOT BE ALTERED. SEE SHEET 12 FOR EXACT CONSTRUCTION. REQUIRED IMPEDANCES WILL BE ACHIEVED BY PCB MFG. INHERENT TO THE DESIGN.




DETAIL "A"  
SCALE: 1X

CUSTOMER NOTICE

LINEAR TECHNOLOGY HAS MADE A BEST EFFORT TO DESIGN A CIRCUIT THAT MEETS CUSTOMER-SUPPLIED SPECIFICATIONS: HOWEVER, IT REMAINS THE CUSTOMER'S RESPONSIBILITY TO VERIFY PROPER AND RELIABLE OPERATION IN THE ACTUAL APPLICATION. COMPONENT SUBSTITUTION AND PRINTED CIRCUIT BOARD LAYOUT MAY SIGNIFICANTLY AFFECT CIRCUIT PERFORMANCE OR RELIABILITY. CONTACT LINEAR TECHNOLOGY APPLICATIONS ENGINEERING FOR ASSISTANCE.

THIS CIRCUIT IS PROPRIETARY TO LINEAR TECHNOLOGY AND SUPPLIED FOR USE WITH LINEAR TECHNOLOGY PARTS.

CONTRACT NO.	 1630 McCarthy Blvd. Folsom, CA 95630 Phone: (408) 432-1999 Fax: (408) 432-1999 LTC Confidential - For Customer Use Only			TITLE: SCHEMATIC	14-Bit, 125 Msps Quad ADC with Integrated Drivers
APPROVALS					
PCB DES. GRIFFITHS					
ENG. D. STUETZLE					
DATE: Monday, December 12, 2011	SHEET 15 OF 15				